onsemi

Initial Product/Process Change Notification

Document #: IPCN25081Z
Issue Date:14 Dec 2022

Title of Change:	Additional wafer fabrication facility, PowerChip located in Taiwan.
Proposed Changed Material First Ship Date:	29 Mar 2024 or earlier if approved by customer
Current Material Last Order Date:	N/A *Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability*.
Current Material Last Delivery Date:	N/A *The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory*
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local onsemi Sales Office or Polen.Pitpit@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Tara.McDonald@onsemi.com
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.

Change Category

Category	**Type of Change**
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor

Description and Purpose:

The company onsemi would like to inform its customers of additional wafer fabrication facility, PowerChip located in Taiwan

There is no change to the orderable part number.

There is no product marking change as a result of this change.

	From	**To**
Wafer Fab Site	Diode, Maine	Diode, Maine PowerChip, Taiwan

Reason / Motivation for Change:	Source/Supply/Capacity Changes
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.

Sites Affected:	
onsemi Sites	**External Foundry/Subcon Sites**
None	Powerchip, Taiwan

Marking of Parts/ Traceability of Change:	Datecode

Qualification Plan:

QV DEVICE NAME: NCV3025833
PACKAGE: PQFN 5x5

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, Vcc=5.5V	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
HAST	JESD22-A110	110°C, 85% RH, 3psig, Vcc=5.5V	528 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Current Part Number	New Part Number	Qualification Vehicle
NCV3025833MTW	N/A	NCV3025833MTW